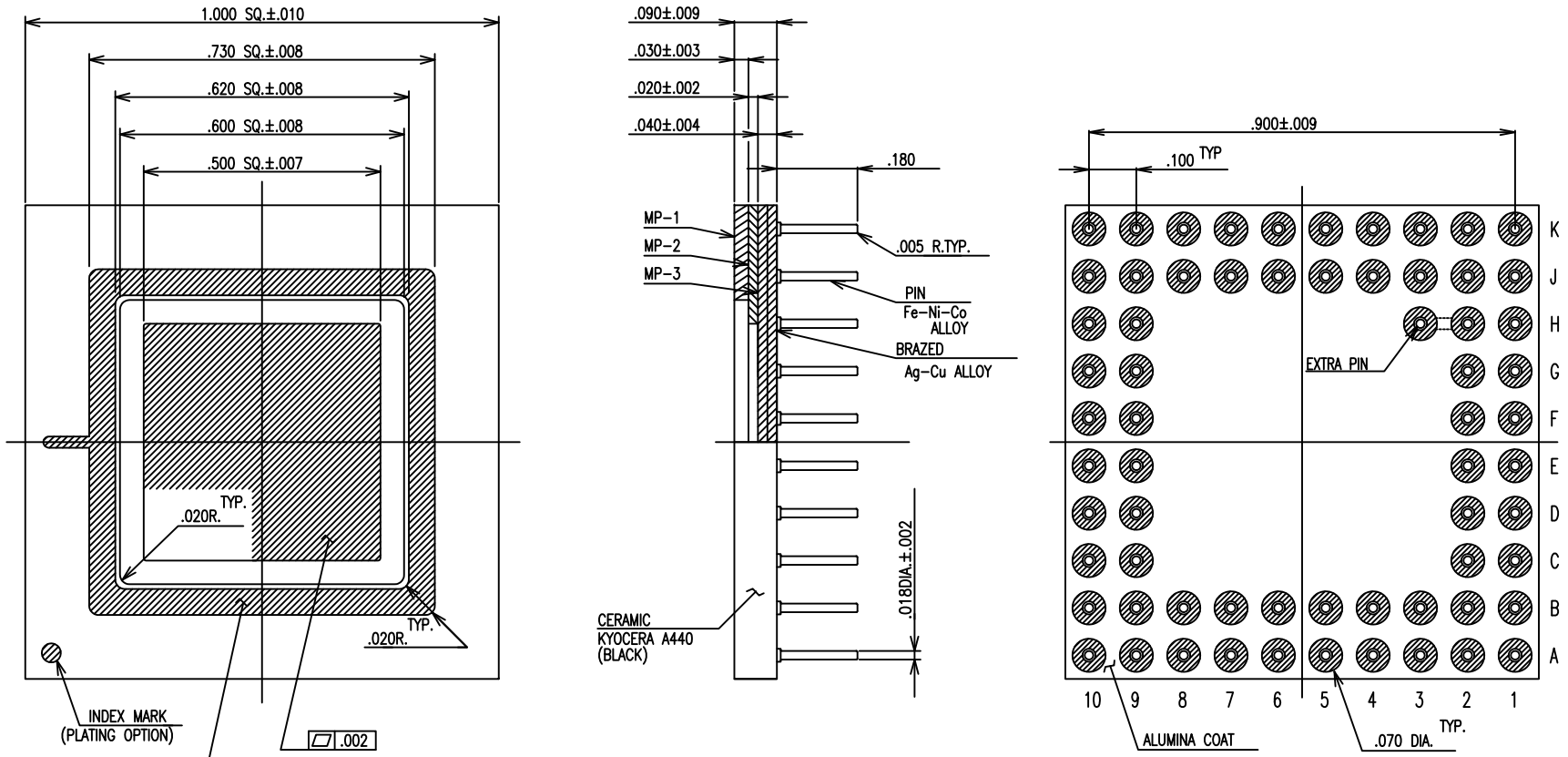
SSM P/N CPG06402



NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.50 OHM MAX.

PB065N703-1 S=0 N=0

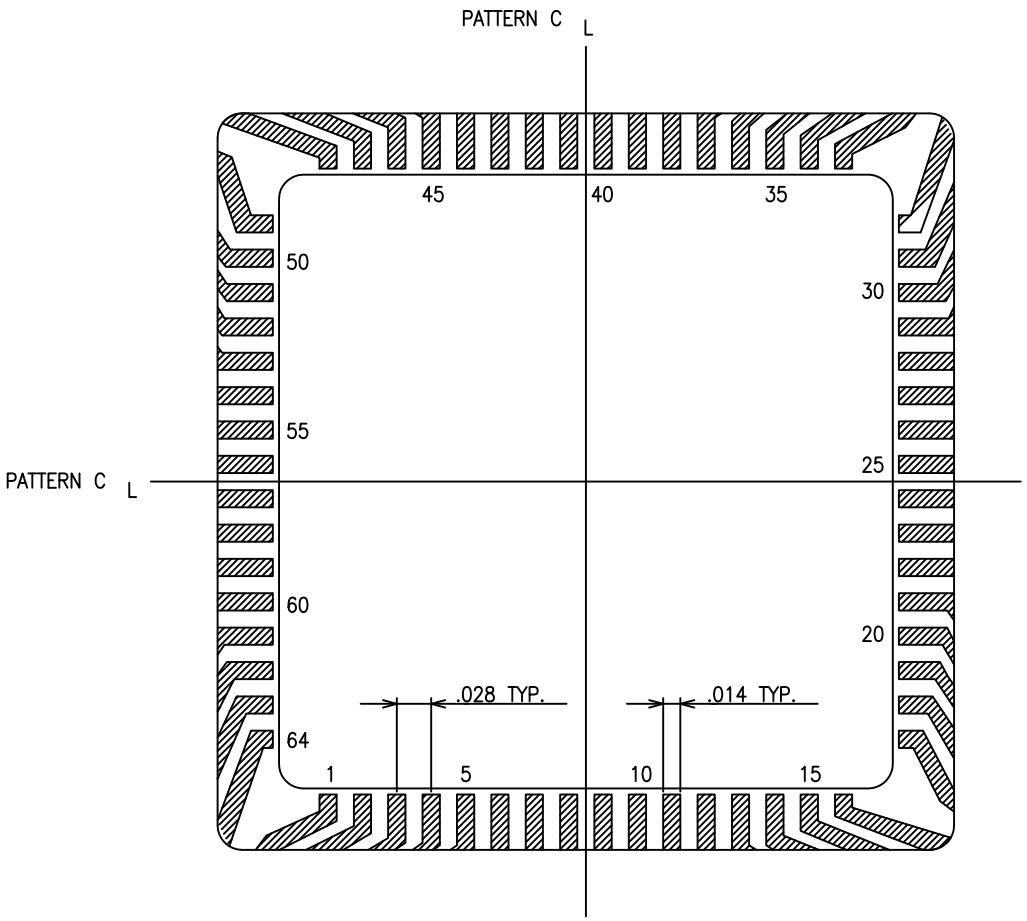
MODIFICATION					
C	REDRAWN (CONVERTED CAD DATA)	DEC.16.'93	K.IM	H.S/K.M	T.A
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
65 PIN GRID ARRAY PACKAGE	±.005	M.K	K.M		NOV.28.'83
SCALE 4/1 — MATERIAL AS INDICATED	THIRD ANGLE PROJECTION				
KYOCERA — KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-P83703-C			SHEET 1/3

SPECTRUM SEMICONDUCTOR MATERIALS, INC.

Ph: 408.435.5555 email: ssm_sales@spectrum-semi.com

SSM P/N CPG06402



BONDING PATTERN

MODIFICATION											
						NAME 65 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
								M.K	K.M		NOV.28.'83
						SCALE 10/1	MATERIAL	THIRD ANGLE PROJECTION			
C	REDRAWN (CONVERTED CAD DATA)	DEC.16.'93	K.IM	H.S/K.M	T.A	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P83703-C			SHEET 2/3
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						

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SSM P/N CPG06402

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	A1
2	B3
3	A2
4	A3
5	B4
6	A4
7	A5
8	B5
9	A6
10	B6
11	A7
12	B7
13	A8
14	B8
15	A9
16	B9
17	A10
18	C9
19	B10
20	C10

W/B NO.	PIN NO.
21	D9
22	D10
23	E10
24	E9
25	F10
26	F9
27	G10
28	G9
29	H10
30	H9
31	J10
32	J9
33	K10
34	J8
35	K9
36	K8
37	J7
38	K7
39	K6
40	J6

W/B NO.	PIN NO.
41	K5
42	J5
43	K4
44	J4
45	K3
46	J3
47	K2
48	J2
49	K1
50	H2
51	J1
52	H1
53	G2
54	G1
55	F1
56	F2
57	E1
58	E2
59	D1
60	D2

W/B NO.	PIN NO.
61	C1
62	C2
63	B1
64	B2

S/R	NC
D/A	NC
EXTRA PIN (H3)	H2

MODIFICATION					
C	REDRAWN (CONVERTED CAD DATA)	DEC.16.'93	K.IM	H.S/K.M	T.A
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
65 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	K.M		NOV.28.'83
SCALE / MATERIAL	THIRD ANGLE PROJECTION				
KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P83703-C			SHEET 3/3

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